

JEDEC STANDARD

Instrumentation Chip Data Sheet for FBDIMM Diagnostic Senselines

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JEDEC SOLID STATE TECHNOLOGY ASSOCIATION



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INSTRUMENTATION CHIP DATA SHEET FOR FBDIMM DIAGNOSTIC SENSELINES

(From JEDEC Board Ballot JCB-06-53, formulated under the cognizance of the JC-40.1 Subcommittee on CMOS/BiCMOS Digital Logic.)

1 Scope

This device is a one-chip spectrum analyzer that operates in the frequency range from 1 to 2 GHz.

It requires no external components except some filtering of the voltage supply (one inductor, one bypass capacitor).

The frequency of the VCO is adjusted by an internal DAC. No PLL loop is used to lock the VCO to a reference frequency. A counter is used to determine the VCO frequency.

The device has a serial I2C data interface.

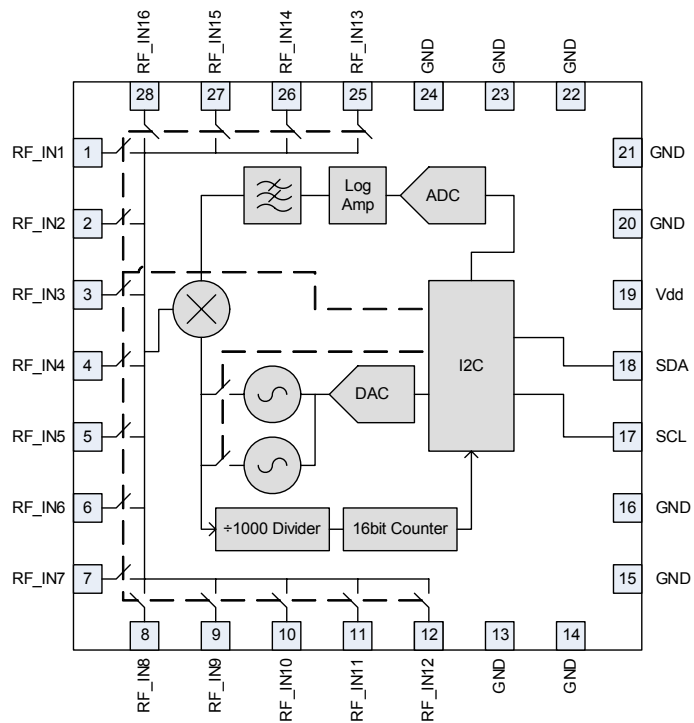
The device is available in a 28 pin TQFN package and is specified over the extended industrial (-40 C to +85 C) temperature range.

2 Features

- Input Frequency Range 1 – 2 GHz
- Integrated Frequency Counter
- 50 dB Dynamic Range
- 3.3 V power supply
- Low Power
- Low Cost
- Small 28 pin TQFN Packages
- Integrated I2C serial interface

2.1 Temperature Range / Package

Functional Diagram / Pin Configuration



2.2 DC electrical characteristics

PARAMETER	CONDITIONS	MIN	TYP	MAX	UNTS
Supply Voltage		2.97	3.3	3.63	V